



Material Content Data Sheet



Sales Product Name		BFS 483 H6327		Issued		19. January 2018		
MA#		MA001612702						
Package		PG-SOT363-6-1		Weight*		6.27 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.002	0.03		288	
	non noble metal	tin	7440-31-5	0.000	0.01		74	
	inorganic material	silicon	7440-21-3	0.016	0.25	0.29	2485	2847
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		92	
	non noble metal	titanium	7440-32-6	0.003	0.05		460	
	non noble metal	chromium	7440-47-3	0.009	0.14		1380	
	non noble metal	copper	7440-50-8	2.869	45.79	45.99	457887	459819
wire	noble metal	gold	7440-57-5	0.013	0.20	0.20	2042	2042
encapsulation	organic material	carbon black	1333-86-4	0.031	0.49		4923	
	plastics	epoxy resin	-	0.663	10.58		105843	
	inorganic material	silicondioxide	60676-86-0	2.391	38.15	49.22	381526	492292
leadfinish	non noble metal	tin	7440-31-5	0.213	3.40	3.40	34029	34029
plating	noble metal	silver	7440-22-4	0.056	0.90	0.90	8971	8971
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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